

PAL16L8AM, PAL16L8A-2M, PAL16R4AM, PAL16R4A-2M PAL16R6AM, PAL16R6A-2M, PAL16R8AM, PAL16R8A-2M STANDARD HIGH-SPEED PAL® CIRCUITS

SRPS016 – D2705, FEBRUARY 1984 – REVISED MARCH 1992

- **Choice of Operating Speeds**
High-Speed, A Devices . . . 25 MHz Min
Half-Power, A-2 Devices . . . 16 MHz Min
- **Choice of Input/Output Configuration**
- **Package Options Include Both Ceramic DIP and Chip Carrier in Addition to Ceramic Flat Package**

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORT S
PAL16L8	10	2	0	6
PAL16R4	8	0	4 (3-state buffers)	4
PAL16R6	8	0	6 (3-state buffers)	2
PAL16R8	8	0	8 (3-state buffers)	0

description

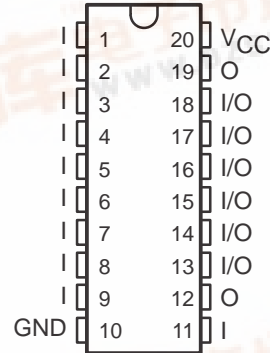
These programmable array logic devices feature high speed and a choice of either standard or half-power devices. They combine Advanced Low-Power Schottky technology with proven titanium-tungsten fuses. These devices will provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allow for quick design of "custom" functions and typically results in a more compact circuit board. In addition, chip carriers are available for further reduction in board space.

The Half-Power versions offer a choice of operating frequency, switching speeds, and power dissipation. In many cases, these Half-Power devices can result in significant power reduction from an overall system level.

The PAL16' M series is characterized for operation over the full military temperature range of –55°C to 125°C.

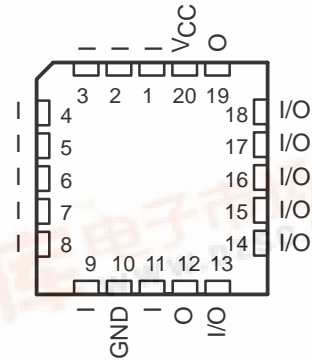
PAL16L8'
J OR W PACKAGE

(TOP VIEW)



PAL16L8'
FK PACKAGE

(TOP VIEW)

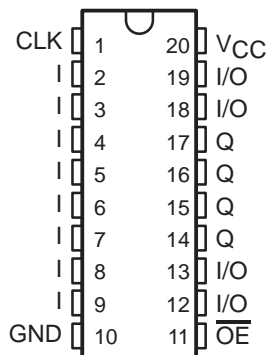


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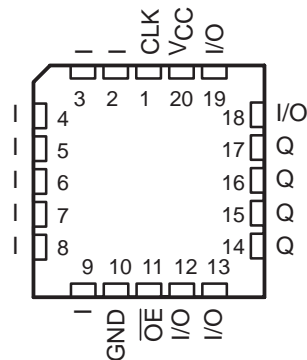
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(TOP VIEW)



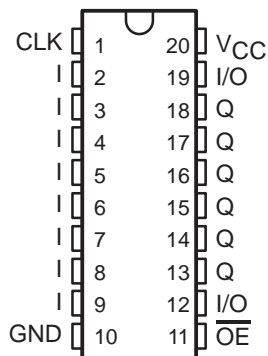
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FK PACKAGE

(TOP VIEW)



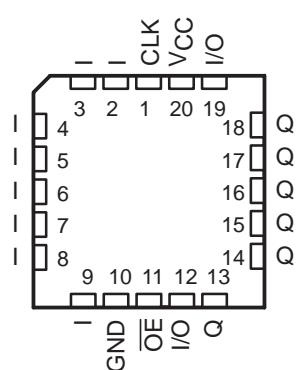
PAL16R6'
J OR W PACKAGE

(TOP VIEW)



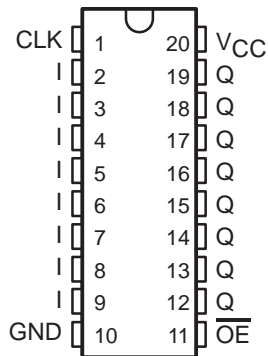
PAL16R6'
FK PACKAGE

(TOP VIEW)



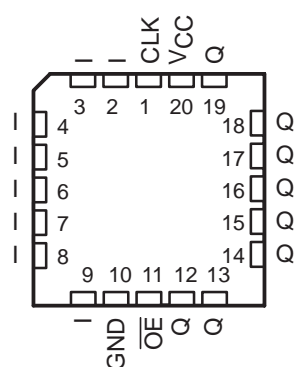
PAL16R8'
J OR W PACKAGE

(TOP VIEW)



PAL16R8'
FK PACKAGE

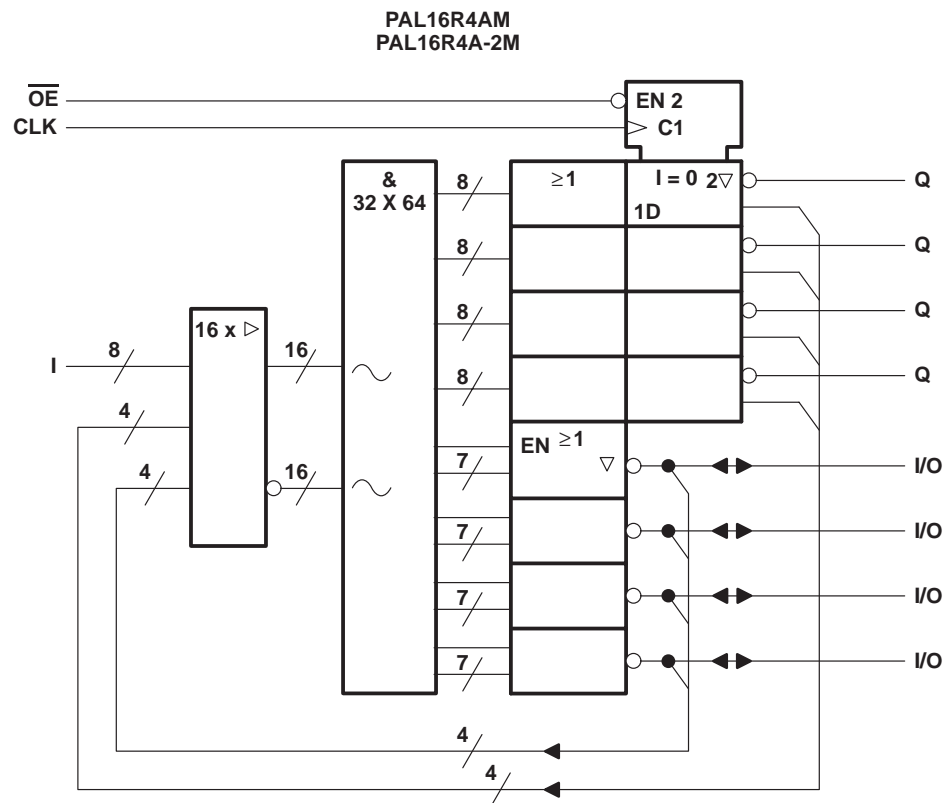
(TOP VIEW)



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PAL16L8AM
PAL16L8A-2M

The diagram illustrates the internal structure of the PAL16L8AM and PAL16L8A-2M devices. It features a 10-bit input **I** connected to a 16x1 multiplexer. The multiplexer's output (16 bits) is connected to a 32x64 AND array. The AND array's output (7 bits) is connected to an OR array. The OR array's output (6 bits) is connected to a 6-bit output **O** and a 6-bit feedback loop back to the multiplexer. The OR array also has an enable input **EN ≥ 1**.

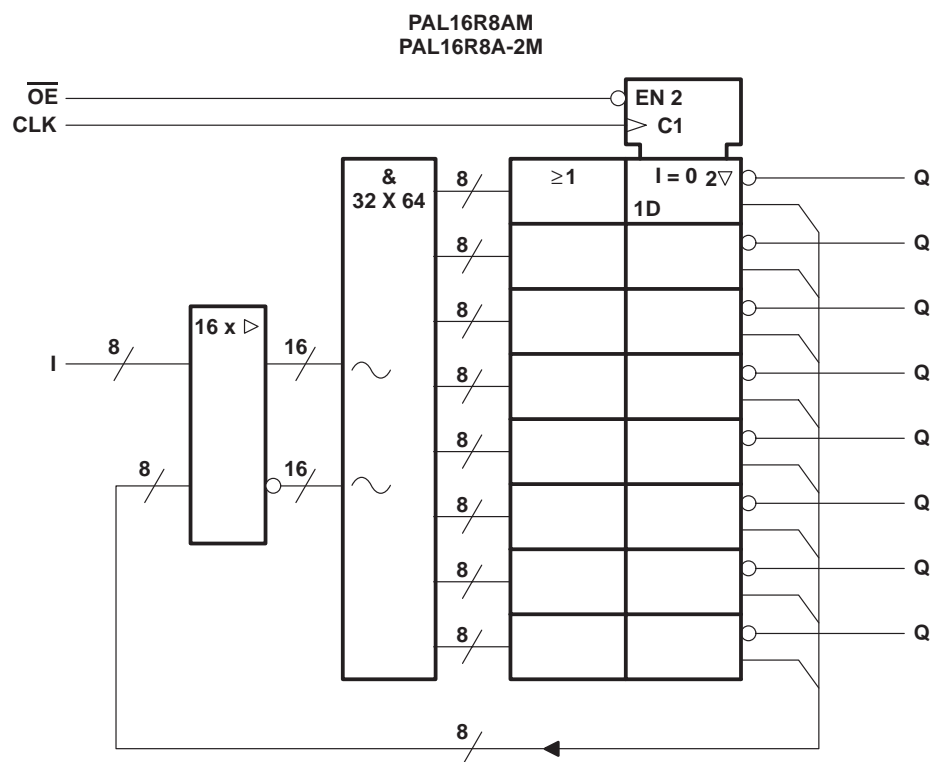
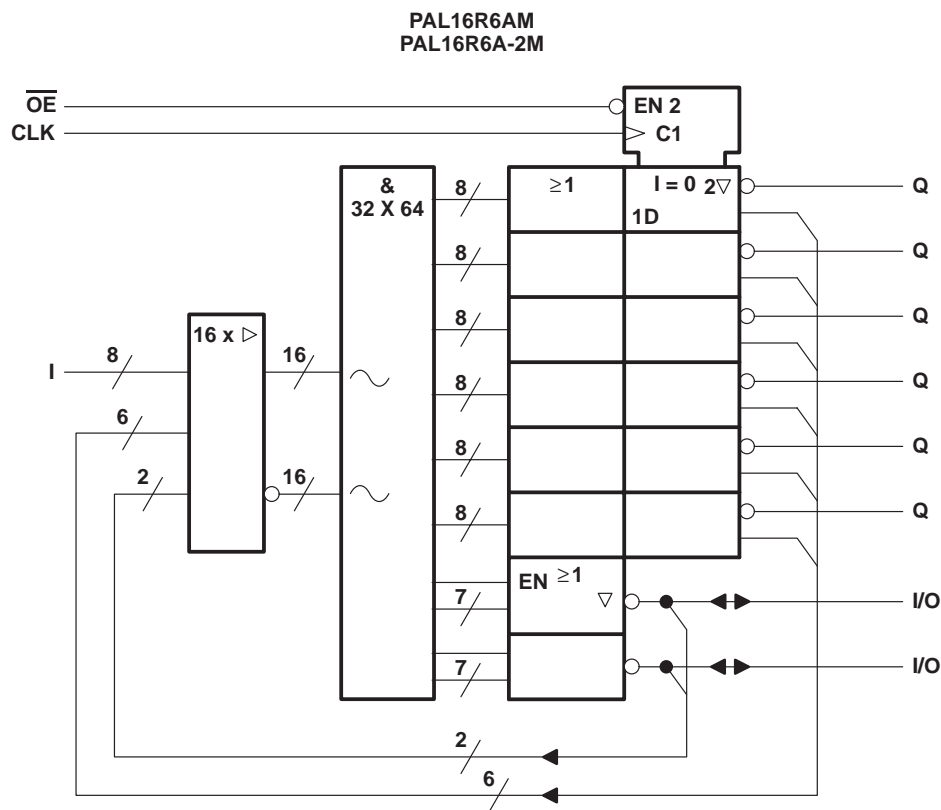


TEXAS
INSTRUMENTS

PAL16R6AM, PAL16R6A-2M, PAL16R8AM, PAL16R8A-2M STANDARD HIGH-SPEED PAL[®] CIRCUITS

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functional block diagrams (positive logic)

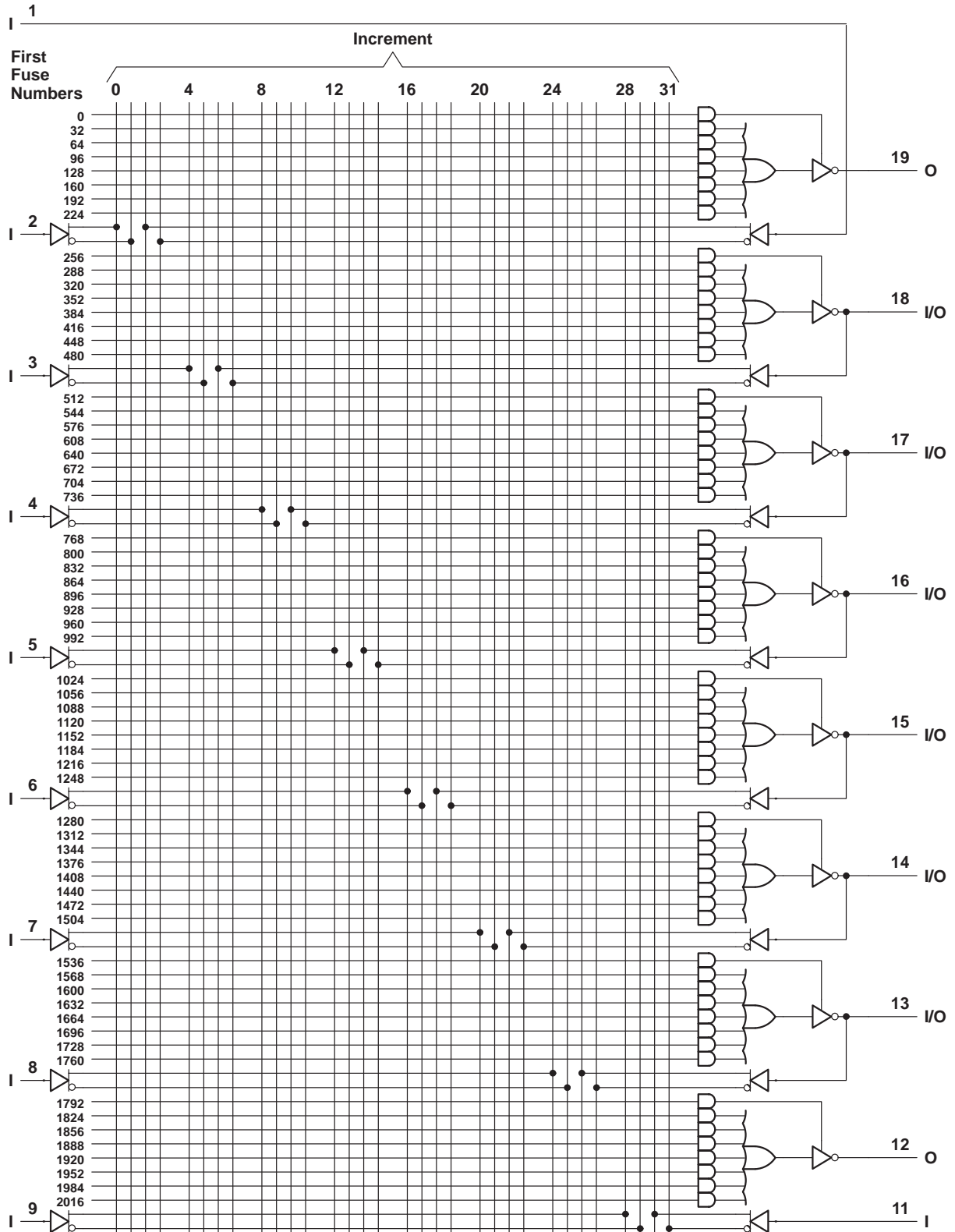


~ denotes fused inputs

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logic diagram (positive logic)

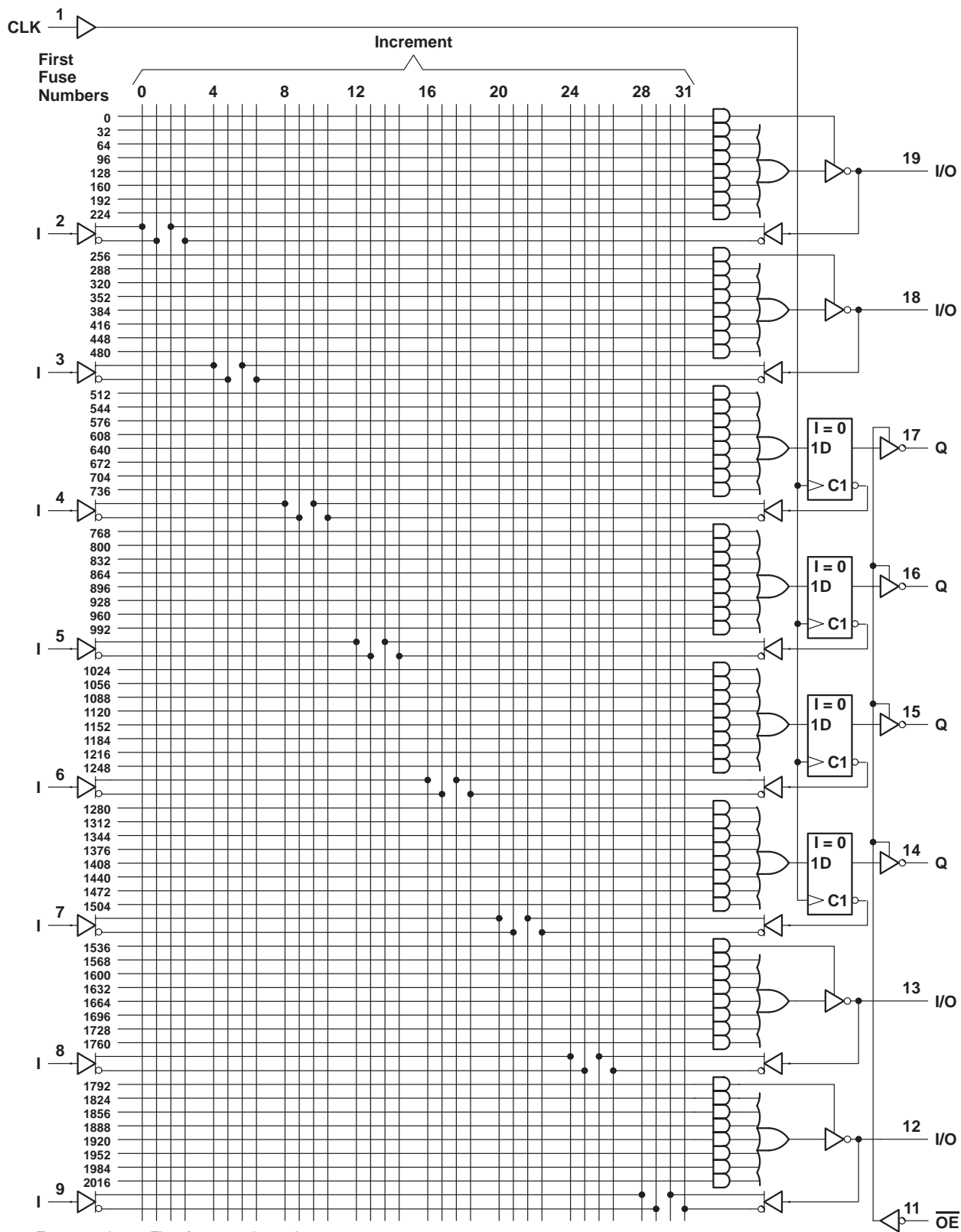


Fuse number = First fuse number + Increment

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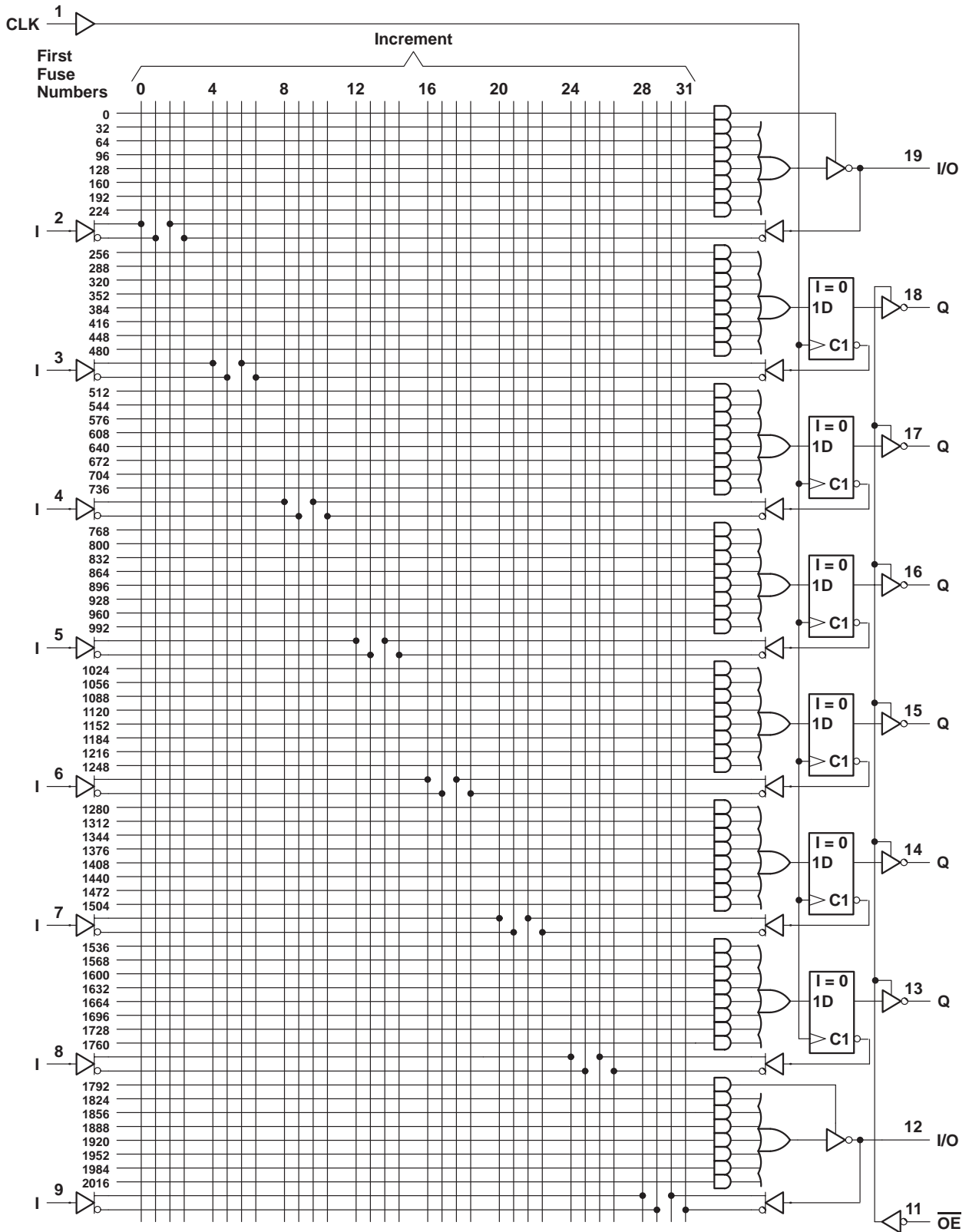
logic diagram (positive logic)



PAL16R6AM, PAL16R6A-2M STANDARD HIGH-SPEED PAL® CIRCUITS

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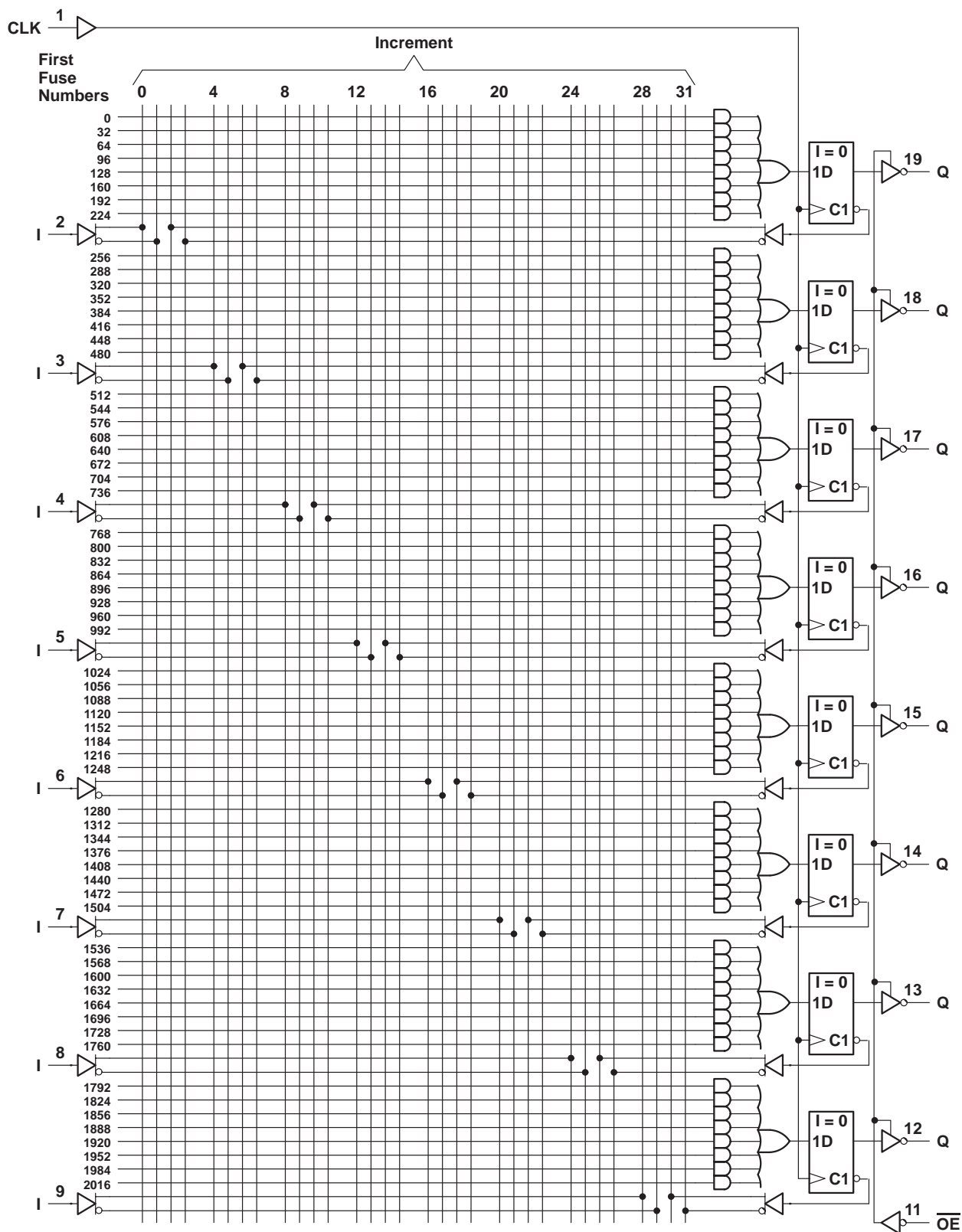
logic diagram (positive logic)



PAL16R8AM, PAL16R8A-2M STANDARD HIGH-SPEED PAL[®] CIRCUITS

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logic diagram (positive logic)



PAL16L8AM, PAL16L8A-2M, PAL16R4AM, PAL16R4A-2M
PAL16R6AM, PAL16R6A-2M, PAL16R8AM, PAL16R8A-2M
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programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	–55°C to 125°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle.

recommended operating conditions

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.5	5	5.5	V
V_{IH} High-level input voltage	2		5.5	V
V_{IL} Low-level input voltage			0.8	V
I_{OH} High-level output current			–2	mA
I_{OL} Low-level output current			12	mA
T_A Operating free-air temperature	–55	25	125	°C

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electrical characteristics over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V,	I _I = –18 mA			–1.5	V
V _{OH}	V _{CC} = 4.5 V,	I _{OH} = –2 mA	2.4	3.2		V
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 12 mA		0.25	0.4	V
I _{OZH}	Outputs	V _{CC} = 5.5 V, V _O = 2.7 V			20	μA
	I/O ports				100	
I _{OZL}	Outputs	V _{CC} = 5.5 V, V _O = 0.4 V			–20	μA
	I/O ports				–100	
I _I	V _{CC} = 5.5 V,	V _I = 5.5 V			0.2	mA
I _{IH}	I/O Ports	V _{CC} = 5.5 V, V _I = 2.7 V			100	μA
	All others				25	
I _{IL}	OE input	V _{CC} = 5.5 V, V _I = 0.4 V			–0.2	mA
	All others				–0.1	
I _{OS} [‡]	V _{CC} = 5.5 V,	V _O = 0.5 V	–30		–250	mA
I _{CC}	V _{CC} = 5.5 V,	V _I = 0, Outputs open		75	180	mA

timing requirements

		MIN	MAX	UNIT
f _{clock}	Clock Frequency	0	25	MHz
t _w	Pulse duration (see Note 2)	Clock high	15	ns
		Clock low	20	
t _{su}	Setup time, input or feedback before CLK [↑]	25		ns
t _h	Hold time, input or feedback after CLK [↑]	0		ns

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock}. The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	TYP [†]	MAX	UNIT
f _{max}			R1 = 390 Ω, R2 = 750 Ω, See Figure 1	25	45		MHz
t _{pd}	I, I/O	O, I/O			15	30	ns
t _{pd}	CLK [↑]	Q			10	20	ns
t _{en}	OE [↓]	Q			15	25	ns
t _{dis}	OE [↑]	Q			10	25	ns
t _{en}	I, I/O	O, I/O			14	30	ns
t _{dis}	I, I/O	O, I/O			13	30	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

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electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.5	V
V_{OH}		$V_{CC} = 4.5\text{ V}$,	$I_{OH} = -2\text{ mA}$	2.4	3.2		V
V_{OL}		$V_{CC} = 4.5\text{ V}$,	$I_{OL} = 12\text{ mA}$		0.25	0.4	V
I_{OZH}	Outputs	$V_{CC} = 5.5\text{ V}$,	$V_O = 2.7\text{ V}$			20	μA
	I/O ports					100	
I_{OZL}	Outputs	$V_{CC} = 5.5\text{ V}$,	$V_O = 0.4\text{ V}$			-20	μA
	I/O ports					-100	
I_I		$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V}$			0.2	mA
I_{IH}	I/O Ports	$V_{CC} = 5.5\text{ V}$,	$V_I = 2.7\text{ V}$			100	μA
	All others					25	
I_{IL}	\overline{OE} input	$V_{CC} = 5.5\text{ V}$,	$V_I = 0.4\text{ V}$			-0.2	mA
	All others					-0.1	
I_{OS}^\ddagger		$V_{CC} = 5.5\text{ V}$,	$V_O = 0.5\text{ V}$	-30		-250	mA
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$V_I = 0$, Outputs open		75	90	mA

timing requirements

		MIN	MAX	UNIT
f_{clock}	Clock Frequency	0	16	MHz
t_w	Pulse duration (see Note 2)	Clock high	25	ns
		Clock low	25	
t_{su}	Setup time, input or feedback before $\text{CLK}\uparrow$	35		ns
t_h	Hold time, input or feedback after $\text{CLK}\uparrow$	0		ns

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock} . The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	TYP [†]	MAX	UNIT
f_{max}			R1 = 390 Ω , R2 = 750 Ω , See Figure 1	16	25		MHz
t_{pd}	I, I/O	O, I/O			25	40	ns
t_{pd}	$\text{CLK}\uparrow$	Q			11	25	ns
t_{en}	$\overline{OE}\downarrow$	Q			20	25	ns
t_{dis}	$\overline{OE}\uparrow$	Q			11	25	ns
t_{en}	I, I/O	O, I/O			25	40	ns
t_{dis}	I, I/O	O, I/O			25	35	ns

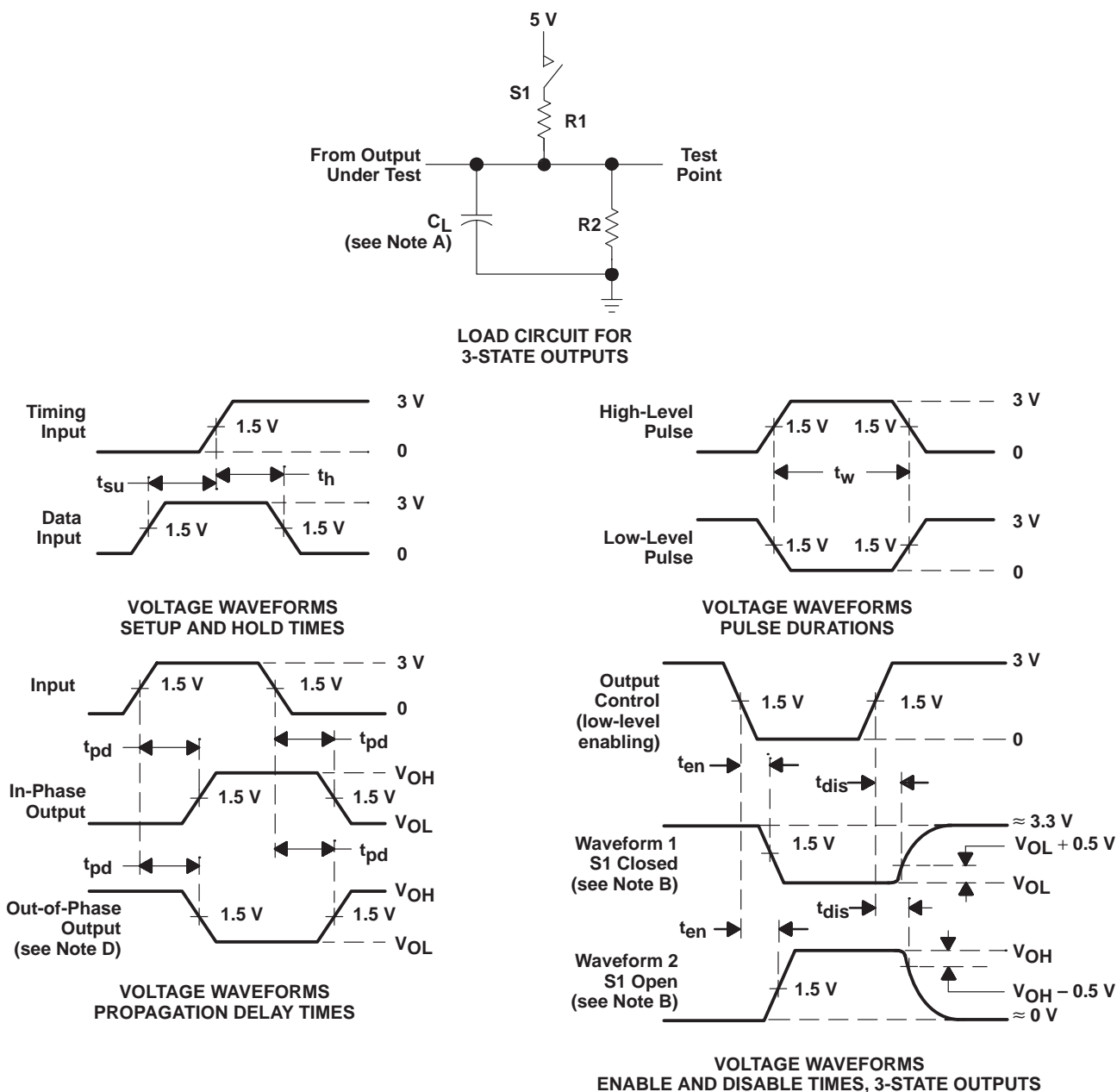
[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en} , 5 pF for t_{dis} .
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses have the following characteristics: $PRR \leq 10$ MHz, t_r and $t_f \leq 2$ ns, duty cycle = 50%
 D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
 E. Equivalent loads may be used for testing.

Figure 1. Load Circuit and Voltage Waveforms

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